

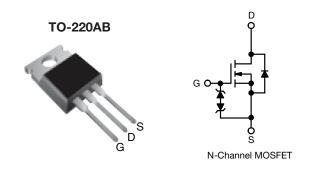
Vishay Siliconix

COMPLIANT

HALOGEN

**FREE** 

# **E Series Power MOSFET**



| PRODUCT SUMMARY                            |                         |       |  |  |
|--|-------------------------|-------|--|--|
| V <sub>DS</sub> (V) at T <sub>J</sub> max. | 850                     |       |  |  |
| R <sub>DS(on)</sub> typ. (Ω) at 25 °C      | $V_{GS} = 10 \text{ V}$ | 0.391 |  |  |
| Q <sub>g</sub> max. (nC)                   | 42                      |       |  |  |
| Q <sub>gs</sub> (nC)                       | 6                       |       |  |  |
| Q <sub>gd</sub> (nC)                       | 12                      |       |  |  |
| Configuration                              | Single                  |       |  |  |

### **FEATURES**

- Low figure-of-merit (FOM) Ron x Qa
- Low effective capacitance (Ciss)
- · Reduced switching and conduction losses
- Ultra low gate charge (Qa)
- Avalanche energy rated (UIS)
- Integrated Zener diode ESD protection
- Material categorization: for definitions of compliance please see <a href="https://www.vishay.com/doc?99912"><u>www.vishay.com/doc?99912</u></a>

### **APPLICATIONS**

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
  - High-intensity discharge (HID)
  - Fluorescent ballast lighting
- Industrial
  - Welding
  - Induction heating
  - Motor drives
  - Battery chargers
  - Renewable energy

| ORDERING INFORMATION            |                 |  |  |
|---------------------------------|-----------------|--|--|
| Package                         | TO-220AB        |  |  |
| Lead (Pb)-free and halogen-free | SiHP11N80AE-GE3 |  |  |

| PARAMETER   |                         |   | SYMBOL                            | LIMIT       | UNIT   |  |
|---|-------------------------|---|-----------------------------------|-------------|--------|--|
| Drain-source voltage                                    |                         |   | V <sub>DS</sub>                   | 800         | V      |  |
| Gate-source voltage                                     |                         |   | $V_{GS}$                          | ± 30        | V      |  |
| Continuous drain current (T <sub>J</sub> = 150 °C)      | V <sub>GS</sub> at 10 V | $T_{\rm C} = 25  ^{\circ}{\rm C}$<br>$T_{\rm C} = 100  ^{\circ}{\rm C}$ | - I <sub>D</sub>                  | 8           |        |  |
|   | V <sub>GS</sub> at 10 V | T <sub>C</sub> = 100 °C   |                                   | 5           | Α      |  |
| Pulsed drain current a                                  |                         |   | I <sub>DM</sub>                   | 22          |        |  |
| Linear derating factor                                  |                         |   |                                   | 0.6         | W/°C   |  |
| Single pulse avalanche energy b                         |                         |   | E <sub>AS</sub>                   | 88          | mJ     |  |
| Maximum power dissipation                               |                         |   | $P_{D}$                           | 78          | W      |  |
| Operating junction and storage temperature range        |                         |   | T <sub>J</sub> , T <sub>stg</sub> | -55 to +150 | °C     |  |
| Drain-source voltage slope $T_J = 125 ^{\circ}\text{C}$ |                         | al / alk  | 70                                | 1//         |        |  |
| Reverse diode dv/dt d                                   |                         |   | dv/dt                             | 2           | - V/ns |  |
| Soldering recommendations (peak temperature) c For 10 s |                         |   | 260                               | °C          |        |  |

### Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature
- b.  $V_{DD}$  = 140 V, starting  $T_J$  = 25 °C, L = 28.2 mH,  $R_{\alpha}$  = 25  $\Omega$ ,  $I_{AS}$  = 2.5 A
- c. 1.6 mm from case
- d.  $I_{SD} \le I_D$ , di/dt = 100 A/ $\mu$ s, starting  $T_J$  = 25 °C



# Vishay Siliconix

| THERMAL RESISTANCE RATINGS       |            |      |      |      |  |
|----------------------------------|------------|------|------|------|--|
| PARAMETER                        | SYMBOL     | TYP. | MAX. | UNIT |  |
| Maximum junction-to-ambient      | $R_{thJA}$ | -    | 62   | °C/W |  |
| Maximum junction-to-case (drain) | $R_{thJC}$ | -    | 1.6  | C/VV |  |

| PARAMETER   | SYMBOL                | TES  | MIN.  | TYP. | MAX.  | UNIT  |      |
|---|-----------------------|--|---|------|-------|-------|------|
| Static  |                       |  |   |      |       |       |      |
| Drain-source breakdown voltage                            | V <sub>DS</sub>       | V <sub>GS</sub> =  | 800   | -    | -     | V     |      |
| V <sub>DS</sub> temperature coefficient                   | $\Delta V_{DS}/T_{J}$ | Reference to 25 °C, I <sub>D</sub> = 1 mA                                |   | -    | 0.8   | -     | V/°C |
| Gate-source threshold voltage (N)                         | V <sub>GS(th)</sub>   | V <sub>DS</sub> =  | V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA             |      | -     | 4     | V    |
| Gate-source leakage                                       | I <sub>GSS</sub>      | V <sub>GS</sub> = ± 20 V   |   | -    | -     | ± 10  |      |
|   |                       | ,  | $V_{GS} = \pm 30 \text{ V}$   | -    | -     | ± 50  | μA   |
| 7   |                       | V <sub>DS</sub> =  | = 800 V, V <sub>GS</sub> = 0 V  | -    | -     | 1     |      |
| Zero gate voltage drain current                           | I <sub>DSS</sub>      | V <sub>DS</sub> = 640 V  | V <sub>DS</sub> = 640 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C |      | -     | 10    | μA   |
| Drain-source on-state resistance                          | R <sub>DS(on)</sub>   | V <sub>GS</sub> = 10 V   | I <sub>D</sub> = 5.5 A  | -    | 0.391 | 0.450 | Ω    |
| Forward transconductance <sup>a</sup>                     | 9 <sub>fs</sub>       | V <sub>DS</sub> = 30 V, I <sub>D</sub> = 5.5 A                           |   | -    | 2.9   | -     | S    |
| Dynamic   |                       |  |   |      | •     |       |      |
| Input capacitance   | C <sub>iss</sub>      | V <sub>GS</sub> = 0 V,   |   | -    | 804   | -     | pF   |
| Output capacitance  | C <sub>oss</sub>      | ,  | V <sub>DS</sub> = 0 V,  |      | 34    | -     |      |
| Reverse transfer capacitance                              | C <sub>rss</sub>      | f = 1 MHz  |   | -    | 5     | -     |      |
| Effective output capacitance, energy related <sup>a</sup> | C <sub>o(er)</sub>    | V <sub>DS</sub> = 0 V to 480 V, V <sub>GS</sub> = 0 V                    |   | -    | 27    | -     |      |
| Effective output capacitance, time related <sup>b</sup>   | C <sub>o(tr)</sub>    |  |   | -    | 162   | -     |      |
| Total gate charge   | Qg                    |  |   | -    | 28    | 42    |      |
| Gate-source charge  | Q <sub>gs</sub>       | $V_{GS} = 10 \text{ V}$  | $V_{GS} = 10 \text{ V}$ $I_D = 5.5 \text{ A}, V_{DS} = 640 \text{ V}$   |      | 6     | -     | nC   |
| Gate-drain charge   | $Q_{gd}$              |  |   | -    | 12    | -     |      |
| Turn-on delay time  | t <sub>d(on)</sub>    | V <sub>DD</sub> = 640 V, I <sub>D</sub> = 5.5 A,                         |   | ı    | 13    | 26    | - ns |
| Rise time   | t <sub>r</sub>        |  |   | ī    | 15    | 30    |      |
| Turn-off delay time                                       | t <sub>d(off)</sub>   | V <sub>GS</sub> =  | $V_{GS} = 10 \text{ V}, R_g = 9.1 \Omega$                               |      | 25    | 50    |      |
| Fall time   | t <sub>f</sub>        | <u> </u>   |   | 1    | 27    | 54    |      |
| Gate input resistance                                     | $R_g$                 | f = 1 MHz, open drain  |   | 0.7  | 1.5   | 3     | Ω    |
| <b>Drain-Source Body Diode Characteristic</b>             | es                    |  |   |      |       |       |      |
| Continuous source-drain diode current                     | I <sub>S</sub>        | showing the  | MOSFET symbol showing the   |      | -     | 8     |      |
| Pulsed diode forward current                              | I <sub>SM</sub>       | integral reverse p - n junction diode                                    |   | -    | -     | 22    | A    |
| Diode forward voltage                                     | V <sub>SD</sub>       | T <sub>J</sub> = 25 °C, I <sub>S</sub> = 5.5 A, V <sub>GS</sub> = 0 V    |   | -    | -     | 1.2   | V    |
| Reverse recovery time                                     | t <sub>rr</sub>       |  |   | -    | 278   | 556   | ns   |
| Reverse recovery charge                                   | Q <sub>rr</sub>       | $T_J = 25$ °C, $I_F = I_S = 5.5$ A, di/dt = 100 A/ $\mu$ s, $V_R = 25$ V |   | -    | 2.9   | 5.8   | μC   |
| Reverse recovery current                                  | I <sub>RRM</sub>      |  |   | -    | 17    | -     | A    |

### Notes

- a.  $C_{oss(er)}$  is a fixed capacitance that gives the same energy as  $C_{oss}$  while  $V_{DS}$  is rising from 0 V to 480 V  $V_{DSS}$
- b.  $C_{oss(tr)}$  is a fixed capacitance that gives the same charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 V to 480 V  $V_{DSS}$



### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

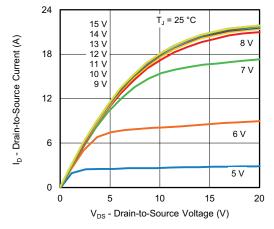


Fig. 1 - Typical Output Characteristics

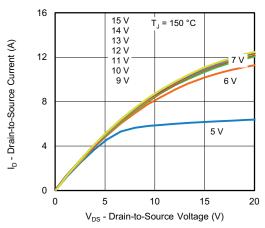


Fig. 2 - Typical Output Characteristics

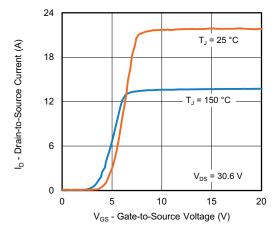


Fig. 3 - Typical Transfer Characteristics

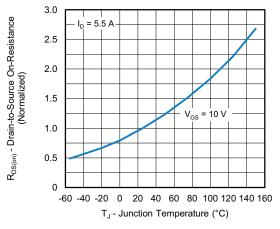


Fig. 4 - Normalized On-Resistance vs. Temperature

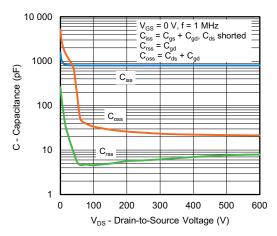


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

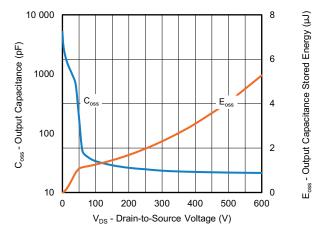


Fig. 6 - Coss and Eoss vs. VDS



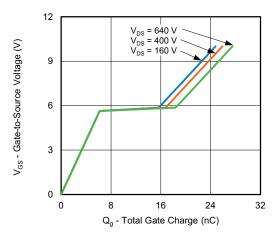


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

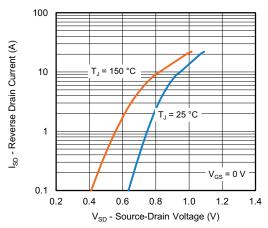


Fig. 8 - Typical Source-Drain Diode Forward Voltage

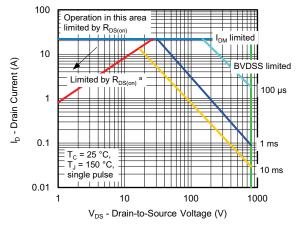


Fig. 9 - Maximum Safe Operating Area

### Note

a.  $V_{GS}$  > minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified

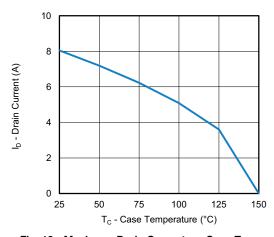


Fig. 10 - Maximum Drain Current vs. Case Temperature

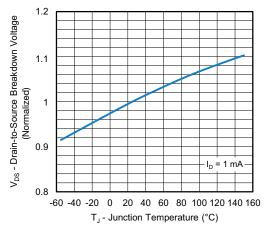


Fig. 11 - Temperature vs. Drain-to-Source Voltage



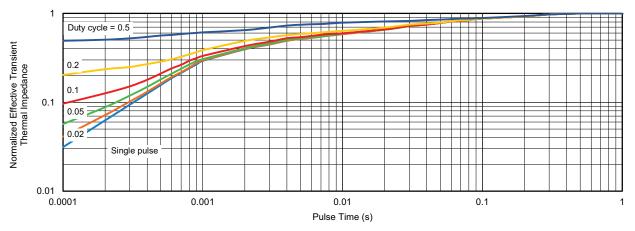


Fig. 12 - Normalized Transient Thermal Impedance, Junction-to-Case

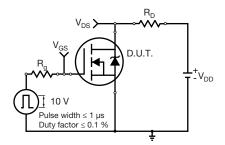


Fig. 13 - Switching Time Test Circuit

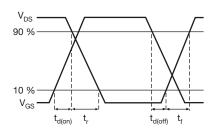


Fig. 14 - Switching Time Waveforms

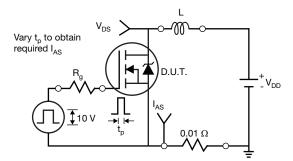


Fig. 15 - Unclamped Inductive Test Circuit

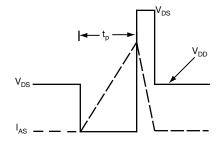


Fig. 16 - Unclamped Inductive Waveforms

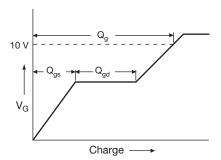


Fig. 17 - Basic Gate Charge Waveform

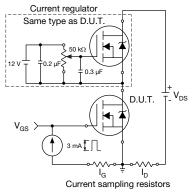


Fig. 18 - Gate Charge Test Circuit



### Peak Diode Recovery dv/dt Test Circuit

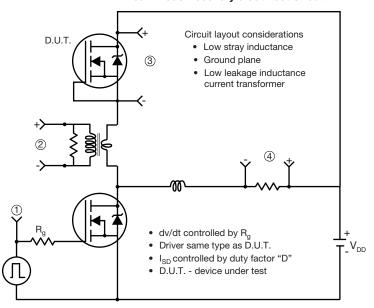




Fig. 19 - For N-Channel

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